Transistors Panasonic

2SA2162G

Silicon PNP epitaxial planar type

For general amplification Complementary to 2SC6036G

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	-15	V	
Collector-emitter voltage (Base open)	V _{CEO}	-12	V	
Emitter-base voltage (Collector open)	V_{EBO}	-5	V	
Collector current	I_{C}	-500	mA	
Peak collector current	I _{CP}	-1	A	
Collector power dissipation	P _C	100	mW	
Junction temperature	T _j	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

■ Package

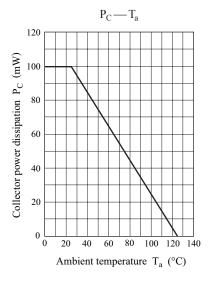
- Code SSSMini3-F2
- Marking Symbol: 2U
- Pin Name
 - 1. Base
 - 2. Emitter
 - 3. Collector

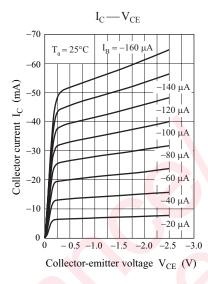
■ Electrical Characteristics T_a = 25°C±3°C

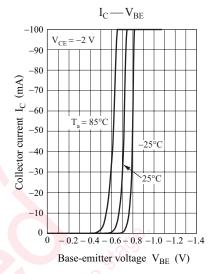
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\rm C} = -10 \mu\text{A}, I_{\rm E} = 0$	-15			V	
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -1 \text{ mA}, I_{\rm B} = 0$	-12)		V	
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}, I_C = 0$	25			V	
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -10 \text{ V}, I_E = 0$			-0.1	μΑ	
Forward current transfer ratio	h_{FE}	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$	270		680	_	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -200 \text{ mA}, I_B = -10 \text{ mA}$			-250	mV	
Transition frequency	f_T	$V_{CB} = -2 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz	
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, f = 1 \text{ MHz}$		4.5		pF	

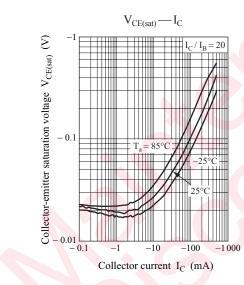
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

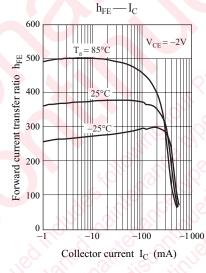
2SA2162G Panasonic

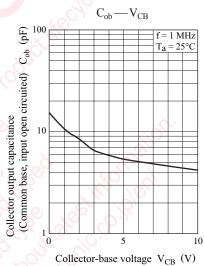


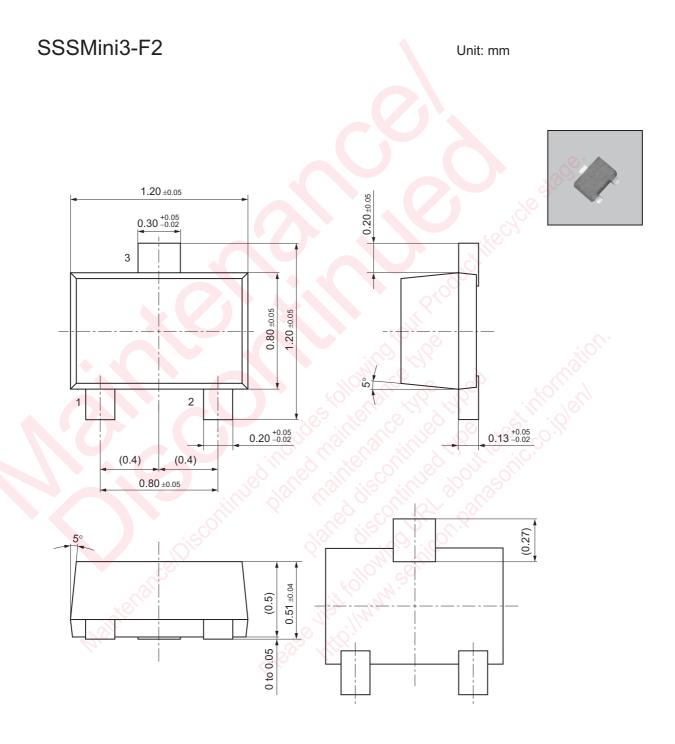












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